

DESCRIPTION

The IS183 low input type optocoupler consists of a GaAs infrared emitting diode optically coupled to an NPN silicon photo transistor in a space efficient Mini Flat package.

FEATURES

- Low Input Current
- CTR guaranteed min 50% at I_F 0.5mA, V_{CE} 5V
- Low Profile Package
- Wide Operating Temperature Range
 55°C to +125°C
- High AC Isolation voltage 3750V_{RMS}
- Lead Free and RoHS Compliant
- Safety Approvals Pending

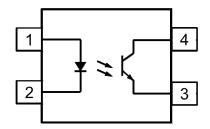
APPLICATIONS

- Computer Terminals
- Industrial System Controllers
- Measuring Instruments
- Signal Transmission between Systems of Differential Potentials and Impedances

ORDER INFORMATION

 Available in Tape and Reel with 3000 pieces per reel





- 1 Anode
- 2 Cathode
- 3 Emitter
- 4 Collector

ABSOLUTE MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Stresses exceeding the absolute maximum ratings can cause permanent damage to the device.

Exposure to absolute maximum ratings for long periods of time can adversely affect reliability.

Input

Forward Current	50mA
Reverse Voltage	6V
Junction Temperature	125 °C

Output

Collector to Emitter Voltage V _{CEO}	80V
Emitter to Collector Voltage V _{ECO}	7V
Collector Current	50mA
Power Dissipation	150mW
Junction Temperature	125 °C

Total Package

Isolation Voltage	$3750V_{RMS}$
Total Power Dissipation	200mW
Operating Temperature	-55 to 125 °C
Storage Temperature	-55 to 125 °C
Lead Soldering Temperature (10s)	260°C

ISOCOM COMPONENTS 2004 LTD

Unit 25B, Park View Road West, Park View Industrial Estate Hartlepool, Cleveland, TS25 1PE, United Kingdom Tel: +44 (0)1429 863 609 Fax: +44 (0)1429 863 581 e-mail: sales@isocom.co.uk

http://www.isocom.com

ISOCOM COMPONENTS ASIA LTD

Hong Kong Office
Block A, 8/F, Wah Hing Industrial Mansions
36 Tai Yau Street, San Po Kong, Kowloon, Hong Kong
Tel: +852 2995 9217 Fax: +852 8161 6292
e-mail: sales@isocom.com.hk



ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$, unless otherwise specified. Typical Values at $T_A = 25^{\circ}C$)

INPUT

Parameter	Symbol	mbol Test Condition		Тур.	Max	Unit
Forward Voltage	V_{F}	$I_F = 10 \text{mA}$			1.6	V
Reverse Current	I_R	$V_R = 5V$			5	μΑ
Terminal Capacitance	C_{IN}	V = 0V, $f = 1KHz$		30	250	pF

OUTPUT

Parameter	Symbol	nbol Test Condition		Тур.	Max	Unit
Collector-Emitter Breakdown Voltage	V_{CEO}	$I_C = 0.5 \text{mA}, I_F = 0 \text{mA}$	80			V
Emitter-Collector Breakdown Voltage	V_{ECO}	$I_E = 0.1 \text{mA}, I_F = 0 \text{mA}$	7			V
Collector Dark Current	I_{CEO}	$V_{CE} = 48V, I_F = 0mA$		10	80	nA

COUPLED

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Current Transfer Ratio	CTR	$I_F = 0.5 \text{mA}, V_{CE} = 5 \text{V}$	50			%
		$I_F = 5mA, V_{CE} = 5V$				
Collector-Emitter Saturation Voltage	V _{CE(sat)}	$I_F = 8mA, I_C = 2.4mA$			0.3	V
Floating Capacitance	C_{f}	V = 0V, $f = 1MHz$		0.6	1	pF
Rise Time	$t_{\rm r}$	$V_{CC} = 10V, I_C = 2mA,$		2	18	μs
Fall Time	t_{f}	$R_L = 100\Omega, f = 100Hz$		3	18	

ISOLATION

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Isolation Voltage	$V_{\rm ISO}$	R.H. = 40% to 60 %, t = 1 min	3750			V_{RMS}
Input - Output Resistance	R _{I-O}	$V_{I-O} = 500 VDC$, R.H. = 40% to 60 %,	5 x 10 ¹⁰	1 x 10 ¹¹		Ω

Device is considered a two terminal device: pins 1 and 2 are shorted together and pins 3 and 4 are shorted together.



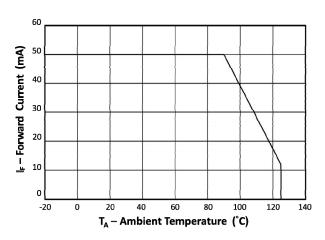


Fig 1 Forward Current vs Ambient Temperature

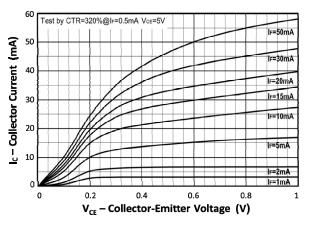


Fig 3 Collector Current vs Collector-Emitter Voltage

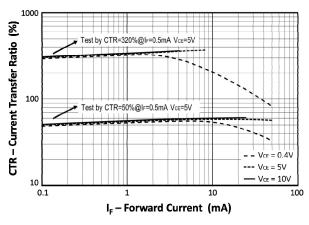


Fig 5 Current Transfer Ratio vs Forward Current

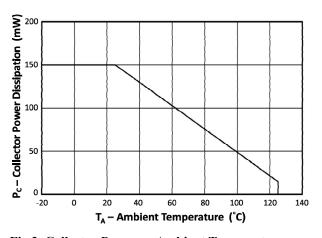


Fig 2 Collector Power vs Ambient Temperature

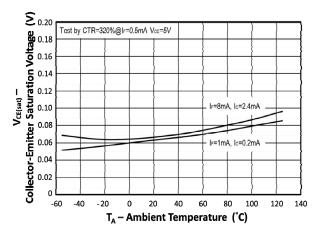


Fig 4 Collector-Emitter Saturation Voltage vs Ambient temperature

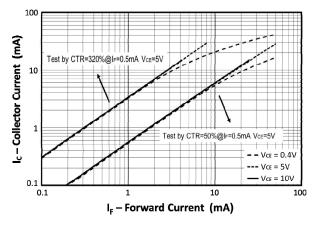


Fig 6 Collector Current vs Forward Current



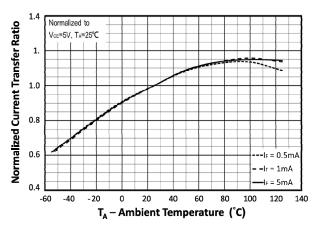


Fig 7 Normalized Current Transfer Ratio vs Ambient Temperature

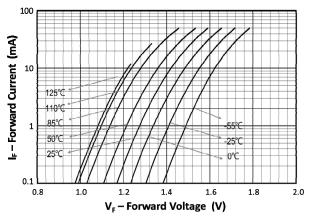


Fig 9 Forward Current vs Forward Voltage

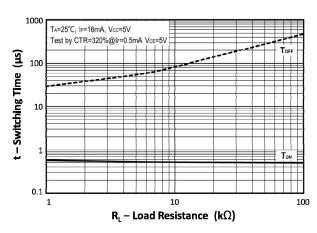


Fig 11 Response Time vs Load Resistance

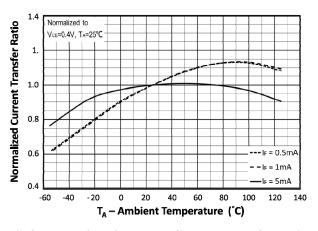


Fig 8 Normalized Saturated Current Transfer Ratio vs Ambient Temperature

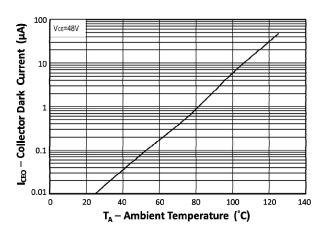


Fig 10 Collector Dark Current vs Ambient temperature

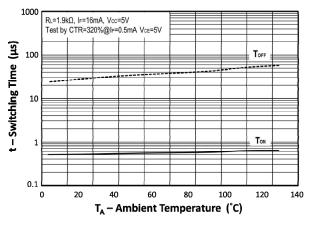
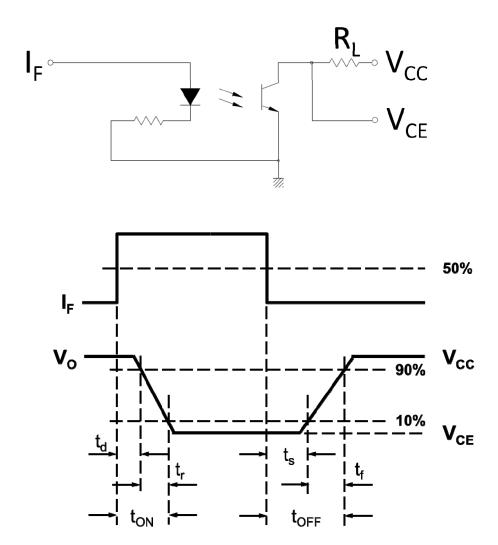


Fig 12 Response Time vs Ambient Temperature





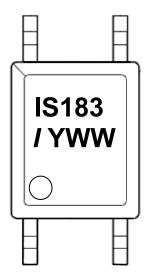
Switching Time Test Circuit and Waveform



ORDER INFORMATION

IS183				
After PN	PN Description Packing quantity			
None	IS183	Surface Mount Tape and Reel	3000 pcs per reel	

DEVICE MARKING



IS183 denotes Device Part Number

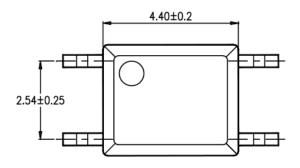
I denotes Isocom

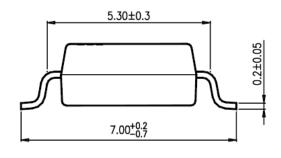
Y denotes 1 digit Year code (A = 2010, B = 2011, etc.)

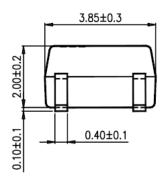
WW denotes 2 digit Week code



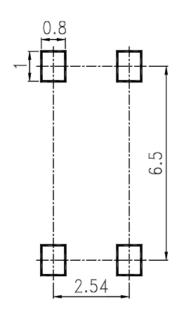
PACKAGE DIMENSIONS in mm





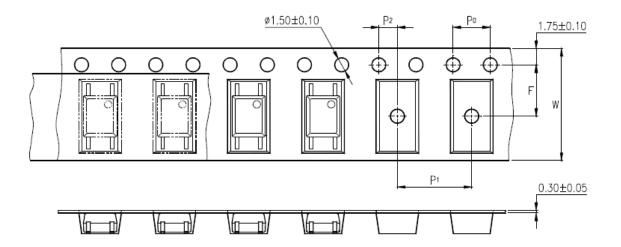


RECOMMENDED PAD LAYPUT FOR SMD (mm)





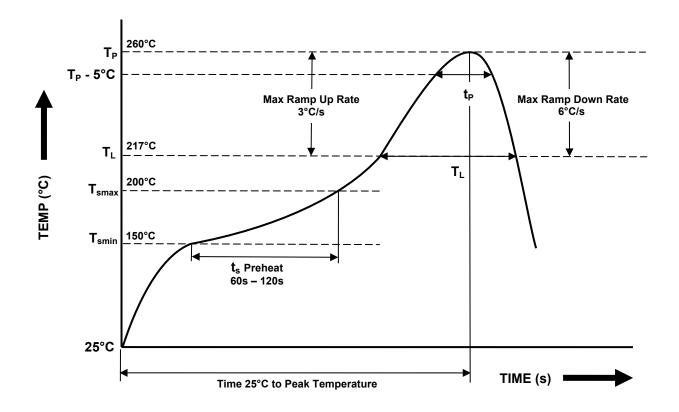
TAPE AND REEL PACKAGING



Description	Symbol	Dimension mm (inch)
Tape Width	W	12 ± 0.3 (0.47)
Pitch of Sprocket Holes	P ₀	4 ± 0.1 (0.15)
Distance of Compartment to Sprocket Holes	F	5.5 ± 0.1 (0.217)
Distance of Compartment to Sprocket Holes	P ₂	2 ± 0.1 (0.079)
Distance of Compartment to Compartment	P ₁	8 ± 0.1 (0.315)



IR REFLOW SOLDERING TEMPERATURE PROFILE One Time Reflow Soldering is Recommended. Do not immerse device body in solder paste.



Profile Details	Conditions
$ \begin{array}{l} \textbf{Preheat} \\ \textbf{- Min Temperature } (T_{SMIN}) \\ \textbf{- Max Temperature } (T_{SMAX}) \\ \textbf{- Time } T_{SMIN} \ to \ T_{SMAX} \ (t_s) \end{array} $	150°C 200°C 60s - 120s
$\begin{tabular}{ll} \textbf{Soldering Zone} \\ - & \mbox{Peak Temperature } (T_P) \\ - & \mbox{Time at Peak Temperature} \\ - & \mbox{Liquidous Temperature } (T_L) \\ - & \mbox{Time within } 5^{\circ}\mbox{C of Actual Peak Temperature } (T_P - 5^{\circ}\mbox{C}) \\ - & \mbox{Time maintained above } T_L \ (t_L) \\ - & \mbox{Ramp Up Rate } (T_L \ \mbox{to } T_P) \\ - & \mbox{Ramp Down Rate } (T_P \ \mbox{to } T_L) \\ \end{tabular}$	260°C 10s max 217°C 30s max 60s - 100s 3°C/s max 6°C/s max
Average Ramp Up Rate (T _{smax} to T _P)	3°C/s max
Time 25°C to Peak Temperature	8 minutes max



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